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(54) ASYMMETRIC-CHANNEL MEMORY SYSTEM

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Mar. 29, 2012, now Pat. No. 9,183,166, filed as application No. PCT/US10/51318 on Oct. 4, 2010.

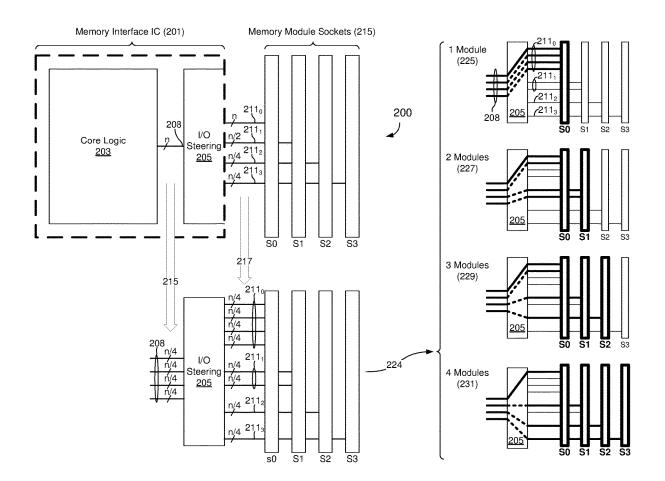
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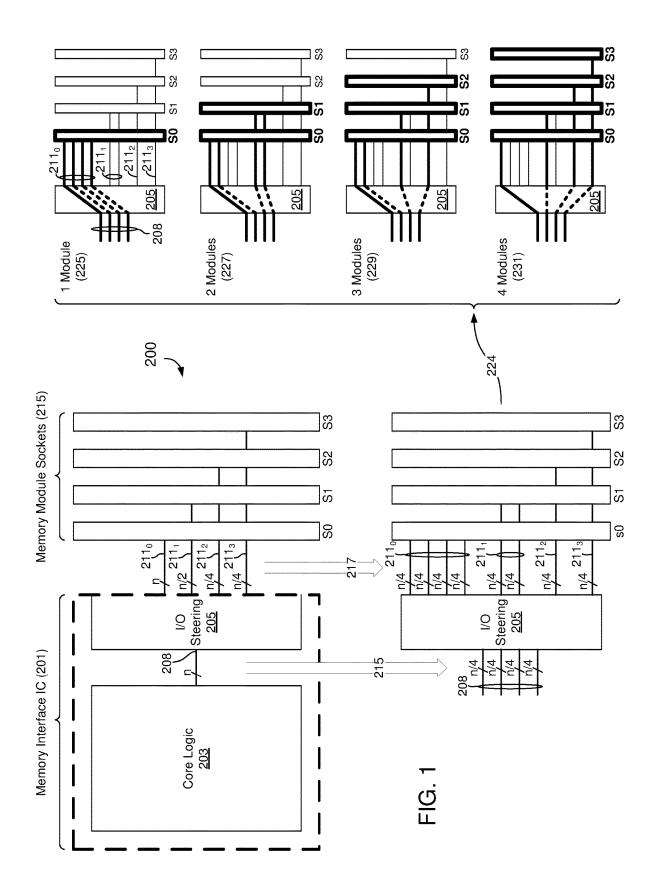
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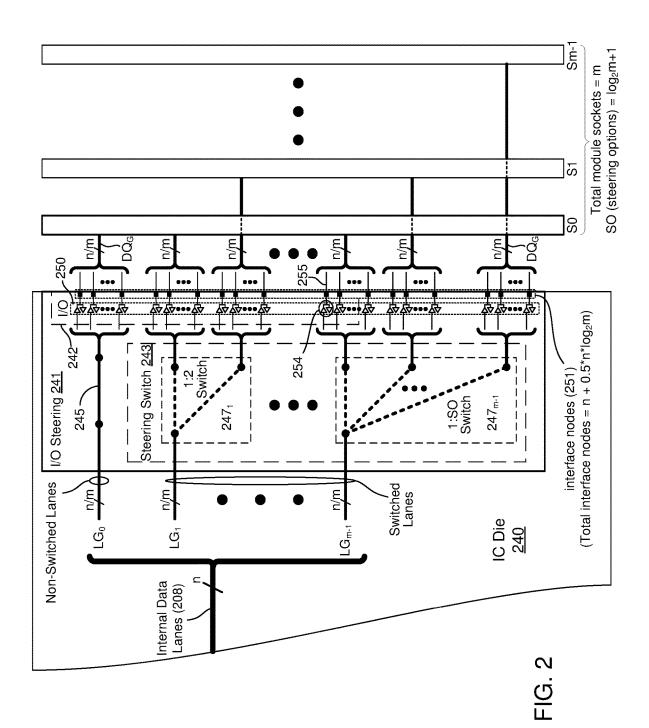
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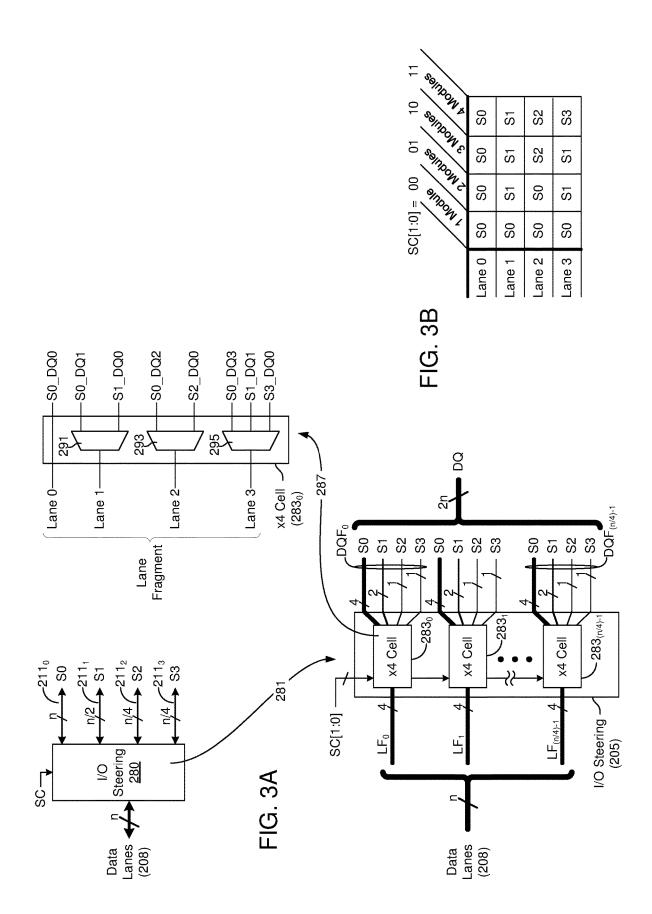
ABSTRACT (57)

An expandable memory system that enables a fixed signaling bandwidth to be configurably re-allocated among dedicated memory channels. Memory channels having progressively reduced widths are dedicated to respective memory sockets, thus enabling point-to-point signaling with respect to each memory socket without signal-compromising traversal of unloaded sockets or costly replication of a fullwidth memory channel for each socket.









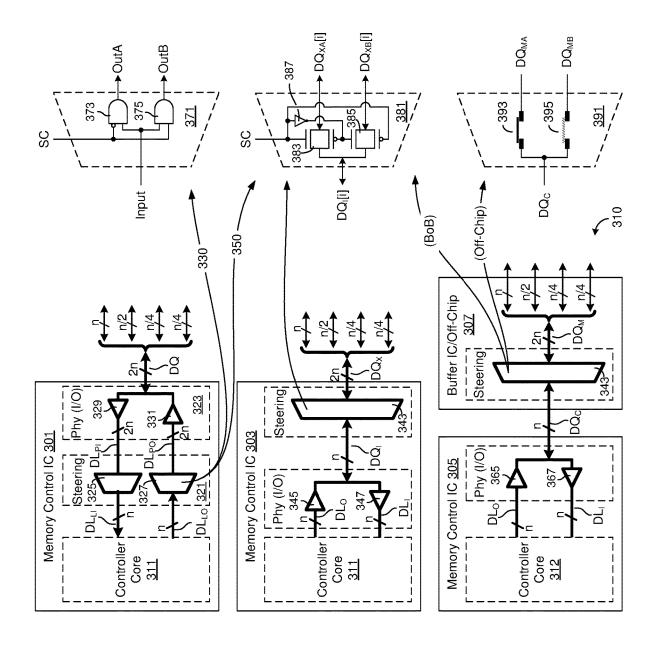
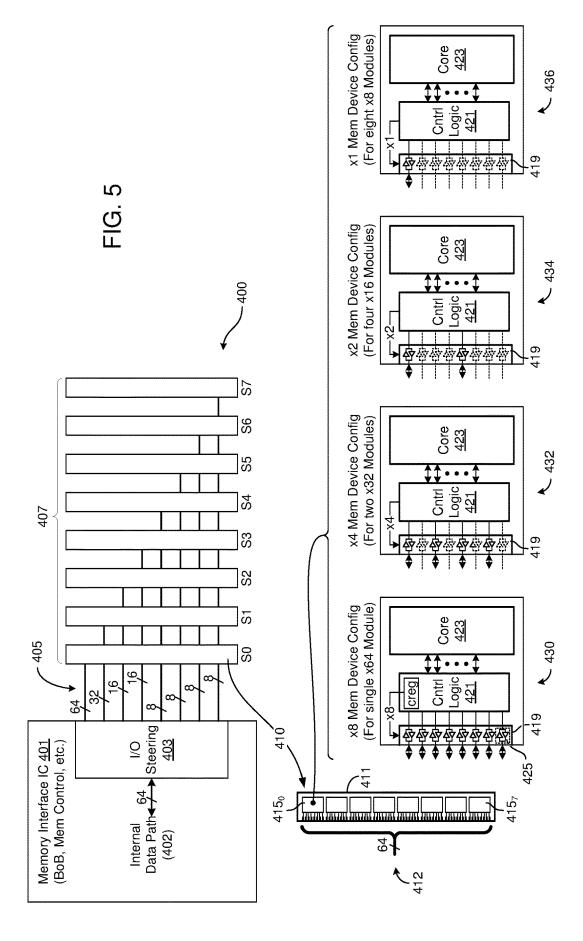


FIG. 4



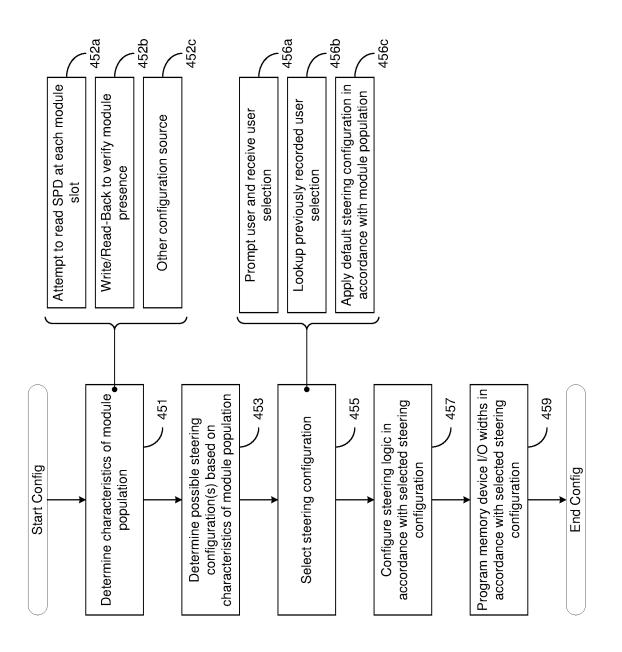


FIG. 6

ASYMMETRIC-CHANNEL MEMORY SYSTEM

[0001] This application is a continuation of U.S. patent application Ser. No. 16/828,570 filed Mar. 24, 2020 (now U.S. Pat. No. 11,200,181), which is a continuation of U.S. patent application Ser. No. 15/992,112 filed May 29, 2018 (now U.S. Pat. No. 10,621,120), which is a continuation of U.S. patent application Ser. No. 15/458,166 filed Mar. 14, 2017 (now U.S. Pat. No. 9,996,485), which is a continuation of U.S. patent application Ser. No. 14/874,324 filed Oct. 2, 2015 (now U.S. Pat. No. 9,632,956), which is a continuation of U.S. patent application Ser. No. 13/499,029 filed Mar. 29, 2012 (now U.S. Pat. No. 9,183,166), which is a 35 U.S.C. § 371 U.S. National Stage of International Patent Application No. PCT/US2010/051318 filed Oct. 4, 2010, which claims priority to U.S. Provisional Patent Application No. 61/286, 371 filed Dec. 14, 2009. Each of the above-identified patent applications is hereby incorporated by reference in its entirety.

[0002] Reflecting on the bandwidth allocation options of Table 1, each of the switched lane groups is switched between as few as two and at least as many as log₂m+1 different steering options. Lane group LG1, for example, is switchably coupled to either socket S0 or socket S1 (two steering options) and thus may be steered by a 1:2 switch element 247_1 as shown. By contrast, lane group LG7 is switchably coupled to one of four different sockets (i.e., log₂8+1=four steering options) so that, in the 8-socket example of Table 1, switch element 247_{m-1} may be implemented by a 1:4 switch), including socket S0 in the singlemodule (x1) configuration, socket S1 in the x2 configuration, socket S3 in the x3-x6 configurations and socket S7 in the x7 and x8 configurations. Thus, steering switch may be formed by m-1 switching elements (one for each of the switched lane groups), including switches having as few as two steering options (switch selections) per data lane, and switches having at least as many as log₂m+1 steering options. Also, because the number of required interface nodes increases by half the base number (n) for each doubling of the number of module sockets, the total number of interface nodes is given by $n{+}0.5{*}n{*}{\log_2}m$ (or $n{+}{}^{1\!/}_{2}{*}n{*}$ (SO-1)), where "*" denotes multiplication. That is, the number of interface nodes is proportional to the log of the socket count (not the socket count itself as in the replicatedchannel system discussed above). Further, the number of interface nodes required per memory socket (and thus the memory channel width and maximum allocable fraction of the system bandwidth for that socket) halves with each doubling of the number of memory sockets, with the sockets in the last-to-be-loaded half of the system having half the minimum number of interface nodes provided to the sockets in the first-to-be-loaded half of the system. Analytically, the number of interface nodes per socket in such an embodiment may be expressed as: $n/(2*roundup(log_2X))$, where '* denotes exponentiation, 'X' is the socket number (an integer between 1 and m that corresponds to the order in which the socket is loaded, with socket number 1 being loaded first), and "roundup()" is a function that rounds its argument up to the nearest integer. For example, in an eight-socket system in accordance with the foregoing, the number of interface nodes per socket may be as follows (more or fewer sockets may be provided in alternative embodiments):

TABLE 2

Socket Position	Socket No.	Interface Nodes (memory channel width)
S 0	1	n
S1	2	n/2
S2	3	n/4
S3	4	n/4
S4	5	n/8
S5	6	n/8
S6	7	n/8
S7	8	n/8

[0003] Detail view 350 illustrates an example of a switching element 381 that may be replicated as necessary within steering circuit 343 (or within steering circuits 325 and/or 327) to provide a bidirectional 1:2 (and 2:1) or unidirectional signal steering function. As shown, an internal signal link, DQ₁ is switchably coupled to each of two external signaling links DQ_{XA} and DQ_{XB} via respective pass gates 383 and 385. Each of the pass gates is implemented by a pair of parallel-coupled transistors that is switched on in response to opposite polarity gate voltages (e.g., PMOS and NMOS transistors in the example shown). A switch control signal is provided to the gate terminals of each pass-gate 383 and 385 in a reverse polarity orientation such that one of the pass gates is switched to a conducting state (i.e., switched on) and the other to a substantially non-conducting state (i.e., switched off), depending on the state of the switch control signal. More specifically, in the embodiment shown, a logic high switch control signal switches on pass gate 383 (through application of the logic high voltage to the NMOS transistor and a logic low voltage, generated by inverted 387, to the PMOS transistor) and switches off pass gate 385 to switchably couple the internal data link, DQ_I[i] exclusively and bidirectionally to external link DQ_{XA}[i]. Conversely, a logic low switch-control signal switches on pass gate 385 (logic low signal applied to PMOS transistor and logic high signal, generated by inverter 387, applied to NMOS transistor) and switches off pass gate 383 to switchably couple DQ_I[i] exclusively and bidirectionally to external link $DQ_{xB}[i]$. Analog switching element **381** may be used as a building block (or the number of pass gates therein increased) to provide a generalized 1:N or N:1 steering function.

[0004] As mentioned, the steering circuitry may also be disposed in a buffer IC 307, thus enabling use of a memory control IC that lacks an internal steering function (e.g., the buffer IC may provide for capacity expansion while maintaining a compatible system integration with legacy systems that utilize memory controllers lacking an internal steering function). In the embodiment shown, for example, buffer IC 307 is coupled between a set of asymmetric memory channels (shown as four channels having widths n, n/2, n/4 and n/4) and a memory control IC 305 having controller core logic 313 and physical I/O circuitry (drivers 365 and receivers 367), but lacking the above-described signal steering function. More specifically, the buffer IC 307 includes a steering circuit 361 and memory-side interface (indicated conceptually by links DQ_{M} to the asymmetric memory channels, as well as a controller-side interface (indicated by links DQ_{c}) to the memory control IC **305**. The buffer IC may be mounted to a motherboard or other substrate (thus forming a buffer-on-board) or together with the memory control IC and/or other IC's in an integrated circuit package 2

(e.g., a system-in-package). With regard to internal organization, the steering circuit **361** may be disposed on either side of the physical memory-side signaling interface (e.g., as in memory IC **301** or memory IC **303**) and thus implemented using either of the multiplexing or switching elements **371** and **381**.

1-20. (canceled)

21. An integrated circuit (IC) component comprising:

- a controller-side data interface, N-bits wide, to be coupled to a memory control component;
- a first memory-side data interface, N-bits wide, to be coupled to a first memory module socket;
- a second memory-side data interface, M-bits wide, to be coupled to a second memory module socket, M being not more than N divided by two; and
- interconnect circuitry coupled between the controller-side data interface and the first and second memory-side data interfaces.

22. The IC component of claim 21 wherein the interconnect circuitry comprises steering circuitry to switchably conduct first data values received via a first portion of the controller-side data interface exclusively to either the first memory-side data interface or the second memory-side data interface.

23. The IC component of claim 22 wherein the steering circuitry to switchably conduct the first data values exclusively to either the first memory-side data interface or the second memory-side data interface comprises circuitry to conduct the first data values exclusively to either the first memory-side data interface or the second memory-side data interface in accordance with a control signal that indicates whether the second memory module socket is populated by a memory module.

24. The IC component of claim 23 wherein the interconnect circuitry is further to conduct second data values received via a second portion of the controller-side data interface exclusively to the first memory-side data interface irrespective of whether the control signal indicates that the second memory module socket is populated by a memory module.

25. The IC component of claim **24** wherein the first and second portions of the controller-side data interface comprise simultaneously receive the first data values and the second data values, respectively.

26. The IC component of claim 23 further comprising a programmable register to output, according to a configuration value stored therein, the control signal that indicates whether the second memory module socket is populated by a memory module.

27. The IC component of claim **21** further comprising a third memory-side data interface, K-bits wide, to be coupled to a third memory module socket, K being not more than N divided by three, and wherein the interconnect circuitry is further coupled between the controller-side data interface and the third memory-side data interface.

28. The IC component of claim **27** further comprising a fourth memory-side data interface, J-bits wide, to be coupled to a fourth memory module socket, J being not more than N divided by four, and wherein the interconnect circuitry is further coupled between the controller-side data interface and the fourth memory-side data interface.

29. The IC component of claim **28** wherein M is equal to N/2, K is equal to N/4 and J is equal to N/4.

30. The IC component of claim **21** wherein the first memory-side interface comprises a first group of M signal transceiver circuits and a second group of M signal transceiver circuits, and the second memory-side interface comprises a third group of M signal transceiver circuits, the IC component further comprising power-control circuitry to disable power to either the second group of M signal transceiver circuits or the third group of M signal transceiver circuits in accordance with a control signal that indicates whether the second memory module socket is populated by a memory module.

31. A method of operation within an integrated circuit (IC) component, the method comprising:

- receiving first and second data values from a memory control component concurrently via respective portions of an N-bit wide controller-side data interface;
- outputting the first data values from the IC component via a first portion of a first memory-side data interface, N-bits wide, to a memory module resident within a first memory module socket; and
- outputting the second data values from the IC component, in accordance with a control value, either via a second portion of the first memory-side data interface or via a second memory-side data interface, the second memory-side data interface being M-bits wide, where M is not more than N divided by two.

32. The method of claim **31** wherein outputting the first data values from the IC component via the first portion of a first memory-side data interface comprises outputting the first data values via the first portion of the first memory-side data interface to a first memory module resident within a first memory module socket.

33. The method of claim **32** wherein outputting the second data values from the IC component either via the second portion of the first memory-side data interface or via the second memory-side data interface comprises outputting the second data values via the second memory-side data interface to a second memory module within a second memory module socket if the control value has a first state and outputting the second data values via the second portion of the first memory-side data interface to the first memory module resident within the first memory module socket if the control value has a second state, the second state indicating that the second memory module socket is unpopulated.

34. The method of claim **32** further comprising outputting the second data values from the IC component either via the second portion of the first memory-side data interface or via the second memory-side data interface concurrently with outputting the first data values via the first portion of the first memory-side data interface.

35. The method of claim **31** further comprising storing the control value within a programmable register of the IC component.

36. The method of claim 31 further comprising:

- receiving third data values from the memory control component via the N-bit wide controller-side data interface concurrently with reception of the first data values and second data values; and
- outputting the third data values from the IC component, in accordance with the control value, via either (i) the second portion of the first memory-side data interface, (ii) the second memory-side data interface, or (iii) a

third K-bit wide memory-side data interface, K being not more than N divided by three.

37. The method of claim 36 further comprising:

receiving fourth data values from the memory control component via the N-bit wide controller-side data interface concurrently with reception of the first data values, second data values and third data values; and

outputting the fourth data values from the IC component, in accordance with the control value, via either (i) the second portion of the first memory-side data interface, (ii) the second memory-side data interface, or (iii) a fourth J-bit wide memory-side data interface, J being not more than N divided by four.

38. The method of claim **37** wherein M is equal to N/2, K is equal to N/4 and J is equal to N/4.

39. The method of claim **37** wherein outputting the first data values, second data values, third data values and fourth data values comprises outputting the first data values, sec-

ond data values, third data values and fourth data values concurrently from the IC component.

40. A integrated circuit component comprising:

- means for receiving first and second data values from a memory control component concurrently via respective portions of an N-bit wide controller-side data interface;
- means for outputting the first data values from the IC component via a first portion of a first memory-side data interface, N-bits wide, to a memory module resident within a first memory module socket; and
- means for outputting the second data values from the IC component, in accordance with a control value, either via a second portion of the first memory-side data interface or via a second memory-side data interface, the second memory-side data interface being M-bits wide, where M is not more than N divided by two.

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